

PROCESS AND APPARATUS FOR DISENGAGING SEMICONDUCTOR
DIE FROM AN ADHESIVE FILM

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ABSTRACT OF THE DISCLOSURE

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10 An apparatus and method for separating a semiconductor die (303) from
an adhesive tape (32) are disclosed. The apparatus includes a blade (34)
mechanically coupled to a blade holder (36), wherein the blade (34) is inclined
relative to the primary surface of the semiconductor die (303). The method
further comprises lifting the semiconductor die (303) while it is attached to the
adhesive tape (32) to assist disengagement. The blade (34) facilitates peeling of
the semiconductor die (303) from the adhesive tape (32) while distributing
stress exerted on the semiconductor die (303) over a larger surface area
15 resulting in reduced die fractures (20).